



## Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2024-07-05
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty statement**

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**Legal statement**

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32U575CGU6	74MI*482XXXU	A	STATSChipPAC SCCJ	2024-07-05
Amount	Unit of measure	Unit type	ST ECOPACK grade	
104	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	0	
Package designator	Package size	Number of instances	Shape	
QFN	7x7	48	Flat	
Comment	Package : A0B9 UFQFPN 7X7X0.55 48L 0.5 MM PITCH 8202210			

QueryList : RoHS Directive 2011/65/EU - 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
,		

QueryList : REACH-23rd January 2024				Response
QUERY				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	0			



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	74MI*482XXXU		103.5780		6000000.0	1000000.0
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	5.856	mg	supplier	die	Silicon (Si)	7440-21-3		5.285	mg	902493	51024
				supplier	metallization	Aluminium (Al)	7429-90-5		0.063	mg	10758	608
				supplier	metallization	Copper (Cu)	7440-50-8		0.188	mg	32104	1815
				supplier	metallization	Nickel (Ni)	7440-02-0		0.001	mg	171	10
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.032	mg	5464	309
				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	1366	77
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	172	10
				supplier	Passivation	Silicon Nitride	12033-89-5		0.045	mg	7684	434
				supplier	Passivation	Silicon Oxide	7631-86-9		0.233	mg	39788	2250
				supplier	Organic Compounds	Acrylic resin	Proprietary		0.140	mg	70000	1352
Glue epoxy (EN4900GC SD)	M-011 Other inorganic materials	1.995	mg	supplier	Organic Compounds	Polybutadiene derivative	Proprietary		0.040	mg	20000	386
				supplier	Organic Compounds	Butadiene copolymer	Proprietary		0.030	mg	15000	290
				supplier	Organic Compounds	Acrylate	Proprietary		0.108	mg	54000	1043
				supplier	Organic Compounds	Epoxy resin	Proprietary		0.060	mg	30000	579
				supplier	Organic Compounds	Peroxide	Proprietary		0.016	mg	8000	154
				supplier	Organic Compounds	Additive	Proprietary		0.036	mg	18000	348
				supplier	Metals	Silver (Ag)	7440-22-4		1.565	mg	785000	15109
Encapsulation (EME-G770)	M-011 Other inorganic materials	32.795	mg	supplier	Organic Compounds	Epoxy Resin A	Proprietary		0.689	mg	21000	6652
				supplier	Organic Compounds	Epoxy Resin B	Proprietary		0.689	mg	21000	6652
				supplier	Organic Compounds	Phenol Resin A	Proprietary		0.689	mg	21000	6652
				supplier	Glass	Silica(Amorphous)A	60676-86-0		25.594	mg	780450	247099
				supplier	Glass	Silica(Amorphous)B	7631-86-9		3.782	mg	115320	36514
				supplier	Organic Compounds	Carbon Black	1333-86-4		0.204	mg	6230	1970
				supplier	Metallic compounds	Metal Hydroxide	Proprietary		0.459	mg	14000	4431
				supplier	Organic Compounds	Phenol Resin B	Proprietary		0.689	mg	21000	6652
Bonding wire (Au)	Bonding Wire	0.654	mg	supplier	Metals	Gold (Au)	7440-57-5		0.654	mg	1000000	6314
Plating Anode (Sn)	M-011 Other inorganic materials	1.078	mg	supplier	Metals	Tin (Sn)	7440-31-5		1.078	mg	1000000	10408
Leadframe (C7025 + Ag)	Copper & its alloys	61.200	mg	supplier	Metals	Copper (Cu)	7440-50-8		56.129	mg	917140	541901
				supplier	Metals	Nickel (Ni)	7440-02-0		1.377	mg	22500	13294
				supplier	Metals	Silicon (Si)	7440-21-3		0.159	mg	2600	1535
				supplier	Metals	Magnesium (Mg)	7439-95-4		0.070	mg	1150	676
				supplier	Metals	Silver (Ag)	7440-22-4		3.465	mg	56610	33453